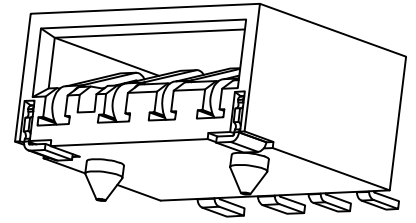
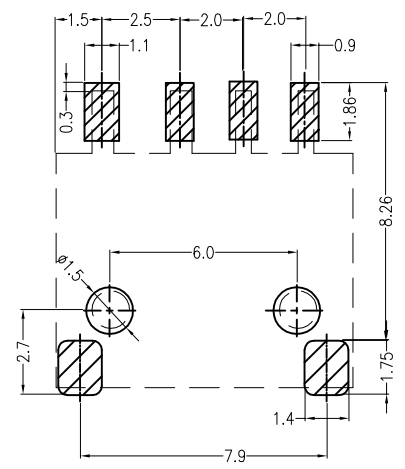
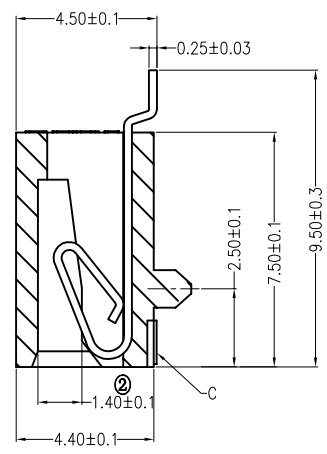
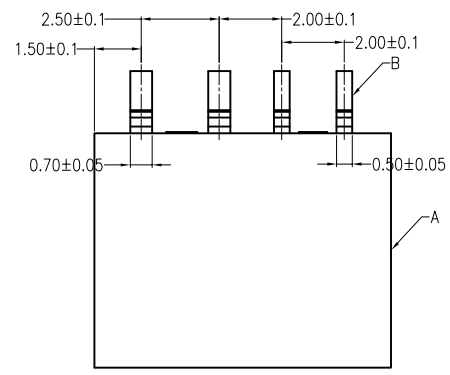


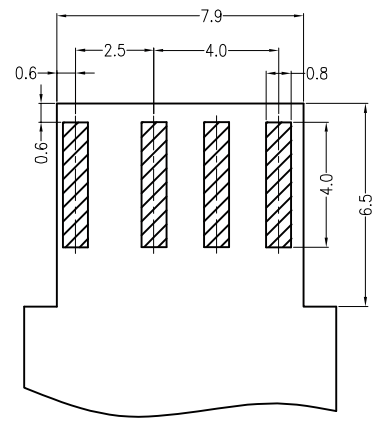
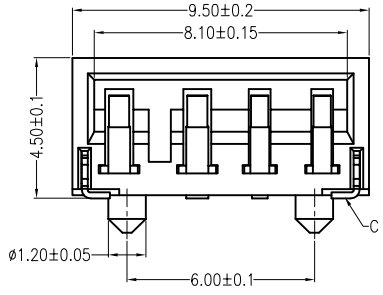
REV	DESCRIPTION	DESIGN	DATE
A0	Release	吴丹平	2016.04.30



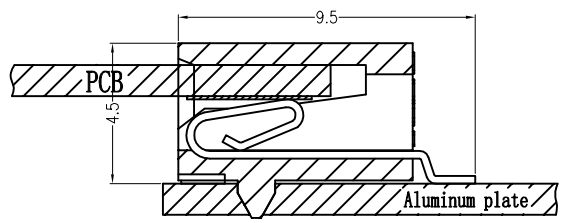
Board Layout

主要技术参数 Main Specifications

- 板厚 (thickness): 1.0mm
- 接触电阻 (Contact resistance): $\leq 20m\Omega$
- 绝缘电阻 (Insulation resistance): $\geq 800M\Omega$
- 额定电压 (Rated voltage): 250/150V AC DC
- 额定电流 (Rated current): 1.0A AC DC
- 耐电压 (Withstand Voltage): 1500V AC/minute
- 温度范围 (Temperature Range): $-25^{\circ}C \sim +105^{\circ}C$



Mating Aluminum plate detail



Assembly Layout

ITEM	COMPONENT	Q'TY	MATERIAL	FINISH
C	Solder Tab	2 PCS	PhosphorBronze	MATTE Sn-plated
B	CONTACT	4 PCS	PhosphorBronze	MATTE Sn-plated
A	PEDESTAL	1 PCS	LCP	UL 94V-0, COLOR:BEIGE

LEDsconn			TITLE: - 2.5/2.0mmPITCH 90°WAFER SMT TYPE	
X.±0.5	X.±5°	USE: CUSTOMER	PART NO.:	
.X±0.3	.X±2°	APPD: 邵敬和	DWG NO.:	
.XX±0.25	.XX±1°	CHKD: 田峰	SCALE	
--	--	DR: 周秀龙	1 : 1	SHEET
UNITS: mm				1 / 1